

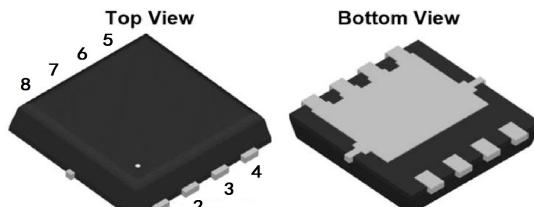
30V N-Channel Mosfet

FEATURES

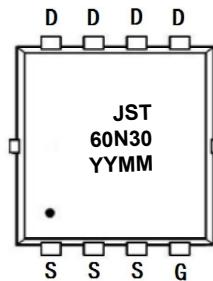
- $R_{DS(ON)} \leq 9.5\text{m}\Omega$ (7mΩ Typ.)
@ $V_{GS}=10\text{V}$
- $R_{DS(ON)} \leq 13.5\text{m}\Omega$ (9mΩ Typ.)
@ $V_{GS}=4.5\text{V}$

APPLICATIONS

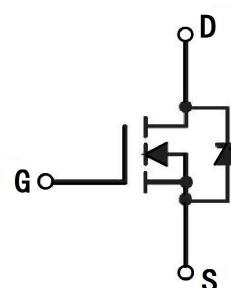
- Consumer electronic power supply
- Motor control
- Isolated DC/DC convertor

PDFN3.3*3.3-8L

1: S	3: S	5: D	7: D
2: S	4: G	6: D	8: D

MARKING

YYMM:Date Code(year&month)

N-CHANNEL MOSFET**MAXIMUM RATINGS ($T_c=25^\circ\text{C}$ unless otherwise noted)**

Symbol	Parameter	Max.	Units
V_{DSS}	Drain-Source Voltage	30	V
V_{GSS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current ^{note1}	54	A
I_{DM}	Pulsed Drain Current ^{note1 note2 note3}	200	A
P_{tot}	Total Power Dissipation ^{note1}	41	W
E_{AS}	Single Pulsed Avalanche Energy	35	mJ
R_{eJC}	Thermal Resistance, Junction to Case ^{note1}	3.13	°C/W
T_J	Junction Temperature	150	°C
T_{STG}	Storage Temperature Range	-55 to +150	°C

MOSFET ELECTRICAL CHARACTERISTICS T_c=25 °C unless otherwise specified

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristics						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D = 250μA	30	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 30V, V _{GS} = 0V, T _J = 25°C	-	-	1	μA
I _{GSS}	Gate to Body Leakage Current	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D = 250μA	1.0	1.7	3.0	V
R _{DS(on)}	Static Drain-Source On-Resistance ^{note4}	V _{GS} =10V, I _D =12A	-	7	9.5	mΩ
		V _{GS} =4.5V, I _D =10A	-	9	13.5	
Dynamic Characteristics ^{note5}						
C _{iss}	Input Capacitance	V _{DS} =15V, V _{GS} = 0V, f = 1.0MHz	-	1070	-	pF
C _{oss}	Output Capacitance		-	165	-	pF
C _{rss}	Reverse Transfer Capacitance		-	118	-	pF
Q _g	Total Gate Charge	V _{DS} =15V, I _D =30A, V _{GS} =10V	-	30.1	-	nC
Q _{gs}	Gate-Source Charge		-	4.5	-	nC
Q _{gd}	Gate-Drain("Miller") Charge		-	1.8	-	nC
Switching Characteristics ^{note5}						
t _{d(on)}	Turn-On Delay Time	V _{GS} = 10V, V _{DS} =30V, R _G =3Ω, R _L =1.5Ω	-	15	-	ns
t _r	Turn-On Rise Time		-	3.5	-	ns
t _{d(off)}	Turn-Off Delay Time		-	31	-	ns
t _f	Turn-Off Fall Time		-	5	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _{SD} =1A, T _J = 25°C	-	0.71	1.0	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0V, I _S =30A, di/dt =100A/μs	-	12	-	ns
Q _{rr}	Reverse Recovery Charge		-	10.5	-	nC

- Notes:
1. Surface Mounted on 1 in² pad area, t≤10 sec
 2. Pulse width ≤10μs, Duty Cycle ≤ 1%.
 3. limited by bonding wire
 4. Pulse test: pulse width ≤300μs, Duty Cycle ≤ 2%.
 5. Guaranteed by design, not subject to production testing

TYPICAL PERFORMANCE CHARACTERISTICS

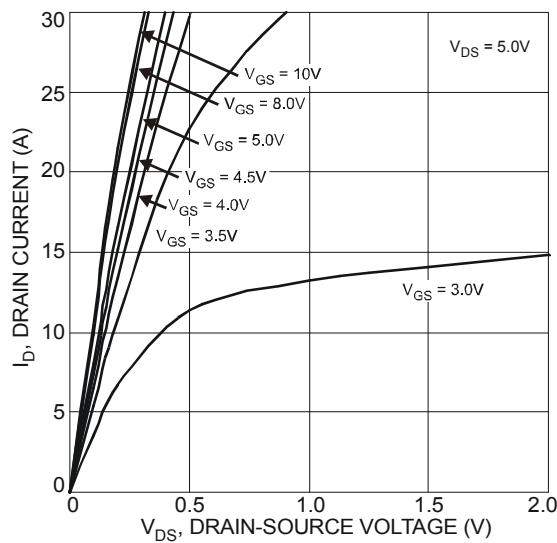


Fig. 1 Typical Output Characteristic

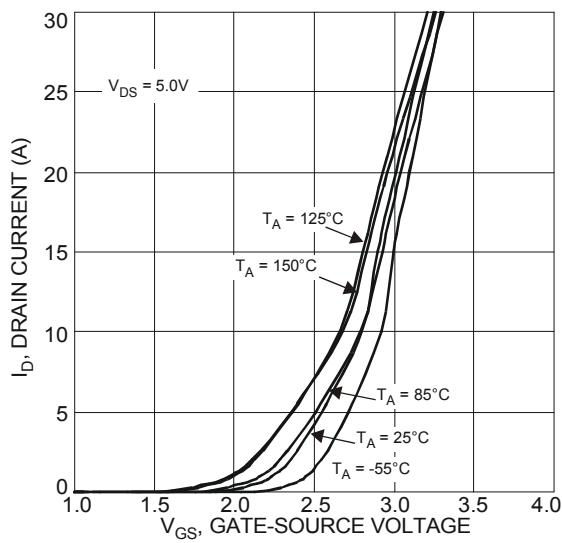


Fig. 2 Typical Transfer Characteristics

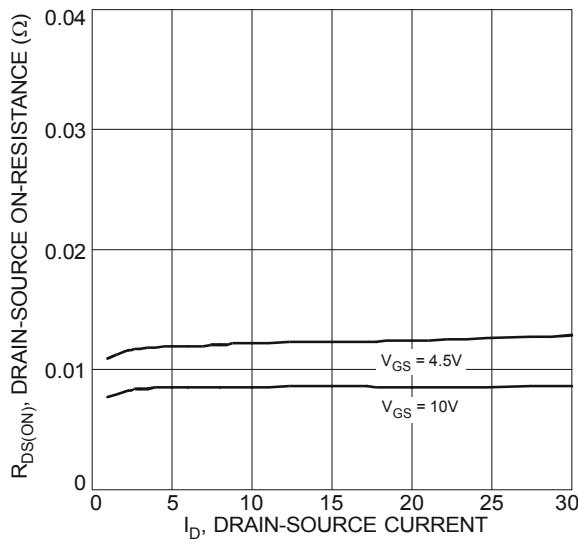


Fig. 3 Typical On-Resistance vs. Drain Current and Gate Voltage

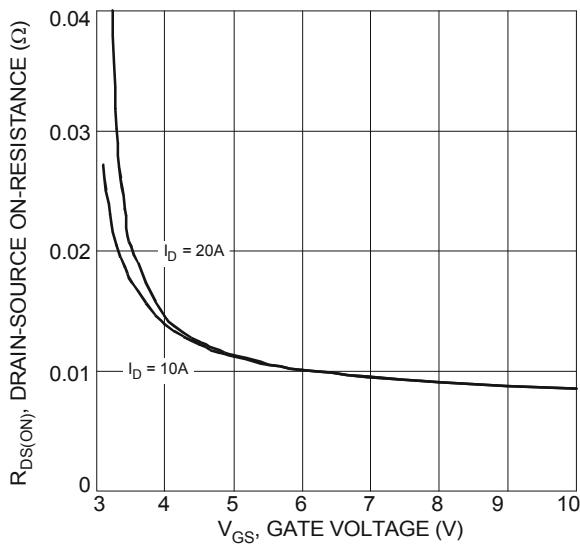


Fig. 4 Typical On-Resistance vs. Gate Voltage

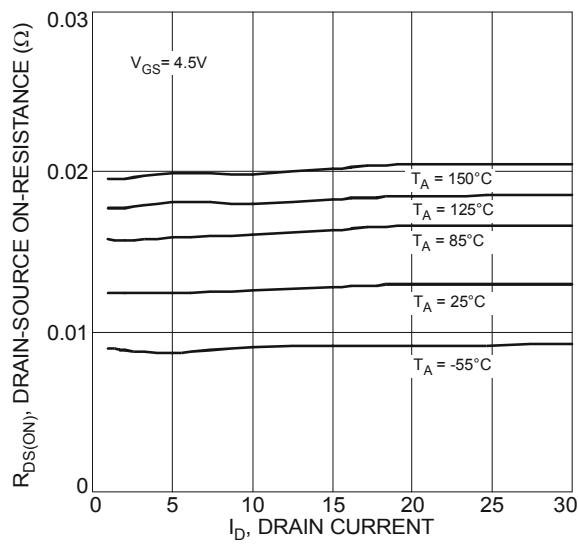


Fig. 5 Typical On-Resistance vs. Drain Current and Temperature

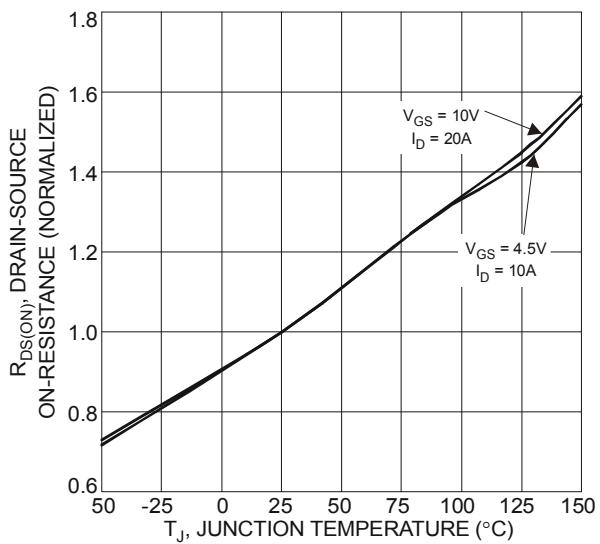
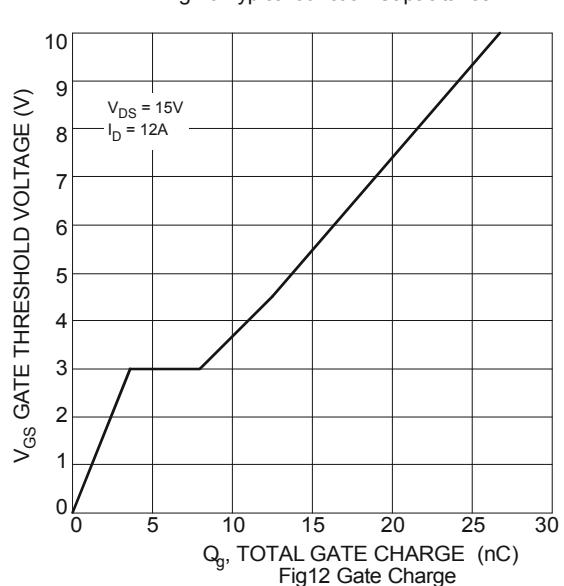
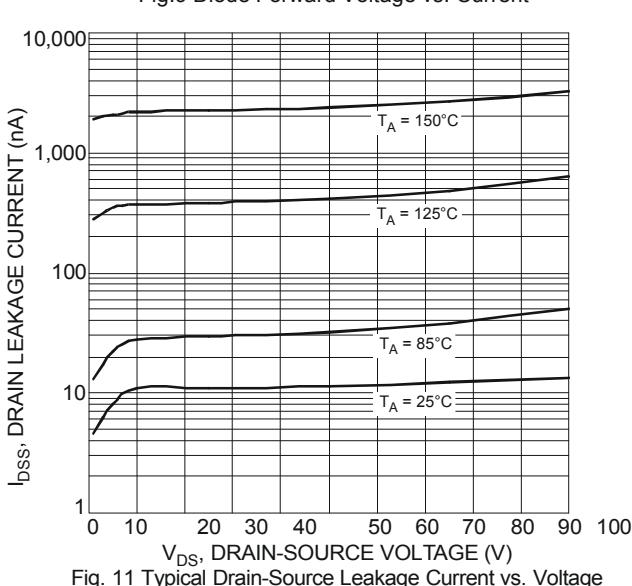
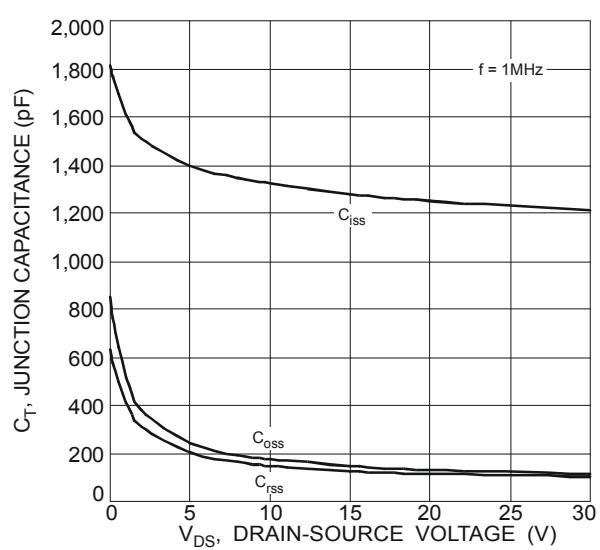
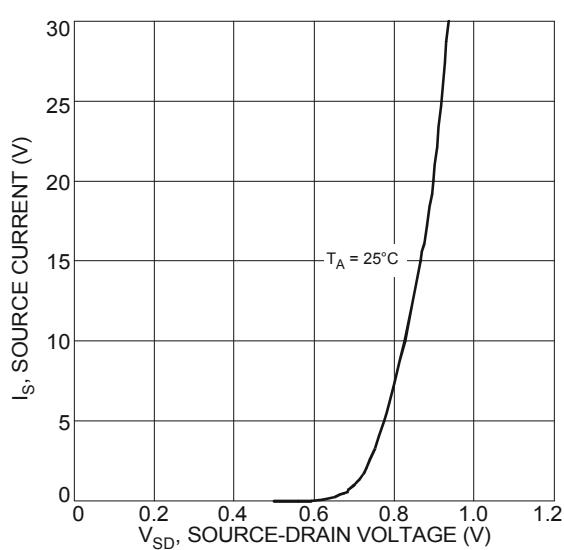
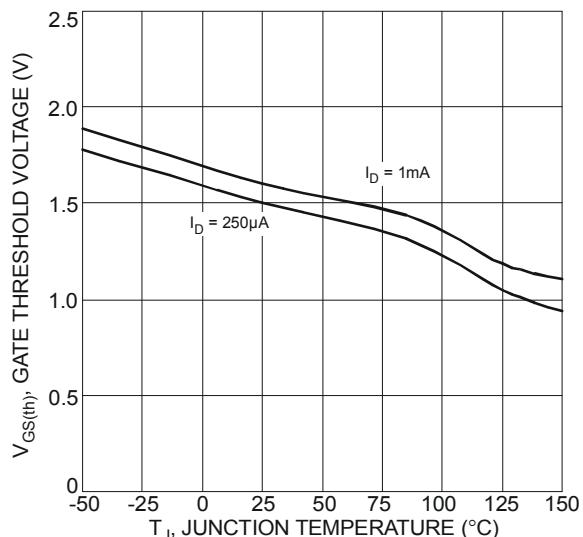
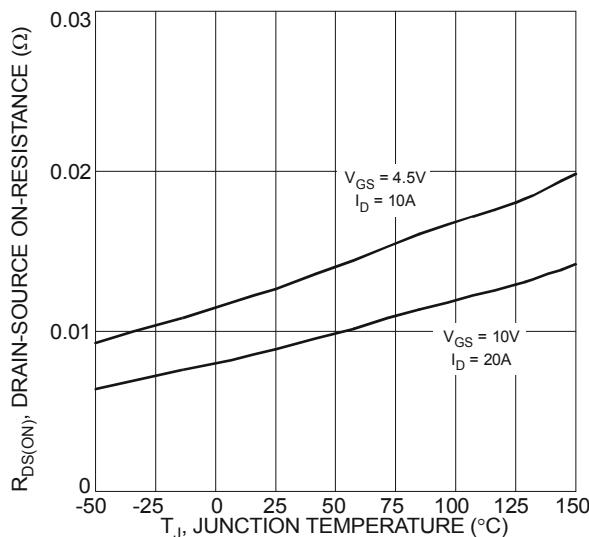
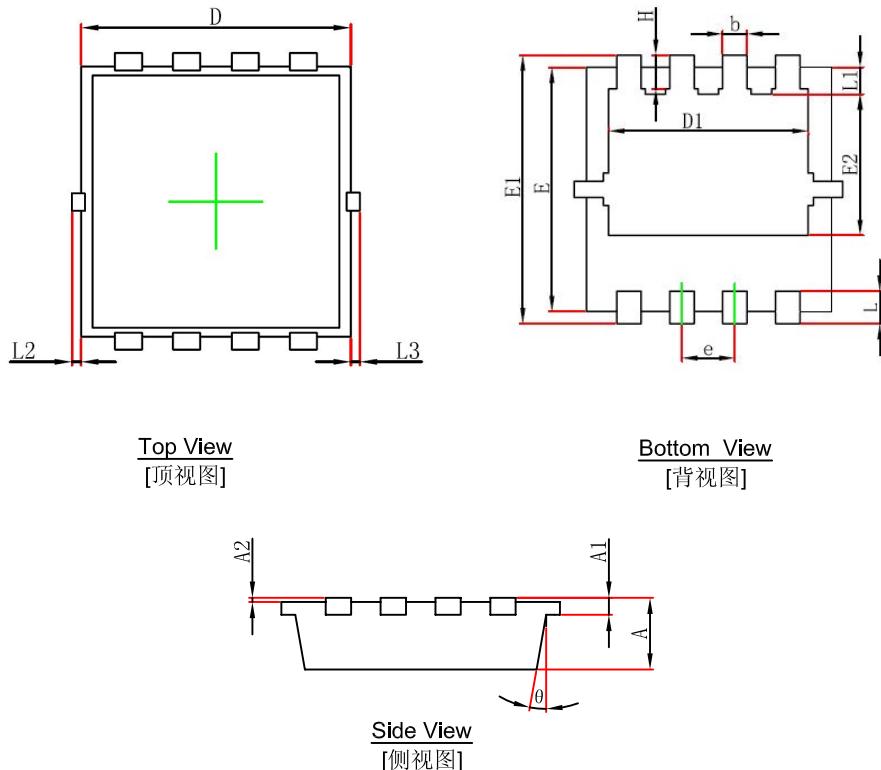


Fig. 6 On-Resistance Variation with Temperature

TYPICAL PERFORMANCE CHARACTERISTICS (cont.)



PDFN3.3*3.3-8L PACKAGE OUTLINE DRAWING



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.650	0.850	0.026	0.033
A1	0.152 REF.		0.006 REF.	
A2	0~0.05		0~0.002	
D	2.900	3.100	0.114	0.122
D1	2.300	2.600	0.091	0.102
E	2.900	3.100	0.114	0.122
E1	3.150	3.450	0.124	0.136
E2	1.535	1.935	0.060	0.076
b	0.200	0.400	0.008	0.016
e	0.550	0.750	0.022	0.030
L	0.300	0.500	0.012	0.020
L1	0.180	0.480	0.007	0.019
L2	0~0.100		0~0.004	
L3	0~0.100		0~0.004	
H	0.315	0.515	0.012	0.020
θ	9°	13°	9°	13°